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(54) METHOD FOR MOUNTING TAB CHIP

(57) Abstract:

PURPOSE: To increase a mounting rate of TAB chips on a printed board by piling up at least two TAB chips and then by mounting these chips on the printed board.

CONSTITUTION: At least two TAB chips 2a, 2a are joined with an adhesive 7 with end faces having no bump 3 faced each other. The bumps 3 are located on an upper and a lower end face of the TAB chip laminated body 2 and then the TAB chip laminated bodies 2 are piled up. Next, the bumps 3 of the lower TAB chip 2a are joined with a printed board 1 with solder 4. Meanwhile, the bumps 3 of the upper TAB chip 2 are connected with one end of wire leads 6 and the other end of the wire leads is joined to a pad of the printed board 1. By this method, a mounting rate on the printed board 1 can be increased and a TAB chip mounting area can be reduced substantially.